Project Documentation

Commodore 1541 VIA/Parallel-Adapter (low P.)

Project number: 149

Revision: 0

Date: 19.08.2020

Commodore 1541-II VIA/Parallel-Adapter Rev. 0

Module Description

Introduction

This adapter board serves as a VIA (6522) adapter for a parallel connection for SpeedDOS in conjunction with a suitable ribbon cable and the User Port Parallel-Adapter (Project 150).

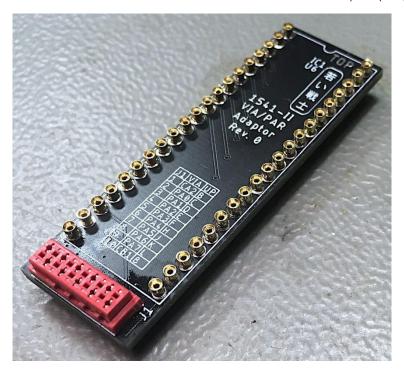


Figure 1: Commodore 1541-II VIA/Parallel-Adapter

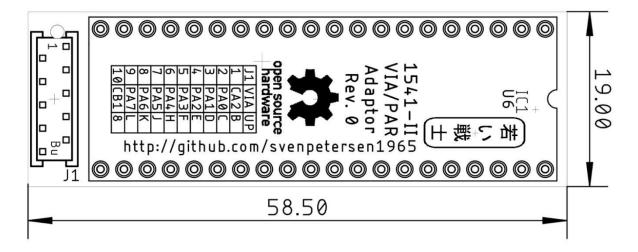


Figure 2: Dimensions

The microMatch connector (10 way) has the following pinout:

VIA (pin)	J2	J2	VIA (pin)
CA2 (39)	1	2	PA0 (2)
PA1 (3)	3	4	PA2 (4)
PA3 (5)	5	6	PA4 (6)
PA5 (7)	7	8	PA6 (8)
PA7 (9)	9	10	CB1 (18)

The via for the parallel data transmission in a 1541 is **U6**.



Figure 3: VIA-Parallel-Adapter installed in a 1541-II

Installation

Four issues have to be taken care of, when installing the VIA-Parallel-Adapter:

- The VIA (U6) should be socketed
- The adapter has to be oriented properly (align the notch of the IC, the adapter and the socket on the 1541-II PCB
- The pins of microMatch connector on the solder side must not make contact with any component leads.
- Pin 2 (PAO) of U6 is connected to GND, which is not required for proper operation (not even with the original Kernal!). **This prevents a proper function** of the parallel adapter. Pin 2 must either be cut off, filed down (a bit) and insulated (Figure 4) or the trace between pin 1 and pin 2 of U6 must be cut.



Figure 4: Shortened pin 2 and insulated socket

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It is a good idea to secure the ribbon cable with an adhesive cable post and a cable tie for strain relief, after the configuration is fully functional. A ribbon cable exiting the case through the breakout for the fuse is pretty common, I did not experience any problems with it, but one person reported a possible source of problems, here.

An alternative way of exiting the case is the left side of the case. A breakout for the ribbon cable has to be filed into the case, though.

The cable making with IDC connectors does not require any special tools, except a (small) vice for compressing the connector after the ribbon cable was inserted properly. In case you don not feel comfortable with this work, consult this write up about cable making: http://tech.guitarsite.de/cable making.html#Ribbon%20Cables

Assembly

The low-profile property of the adapter requires precision round pin sockets. They are usually pretty hard to source and expensive. In July 2020, they were about \$10 plus shipping for 50 each on Ebay USA. It is pretty cheap and easy to salvage them from a precision pin DIP-40 socket (40 pin sockets for less than \$1!). The pin sockets can be popped out of a precision pin socket by applying slight pressure from the bottom side on the "shoulders" of the pin socket with a suitable tweezer (Figure 5). This takes less than 2 minutes per 40 pins.



Figure 5: Salvaging the pin sockets

For proper soldering, the pin sockets need to be aligned. This is accomplished by plugging each on the pin side of a 2^{nd} DIP-40 precision round pin socket (Figure 6). It has t be checked, that all pins are fully inserted. The pins can now be inserted into the solder pads of the PCB from the top side.

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Figure 6: Alignment of the pin sockets

After making sure, that everything is straight (Figure 7), the pins can be soldered from the solder side.

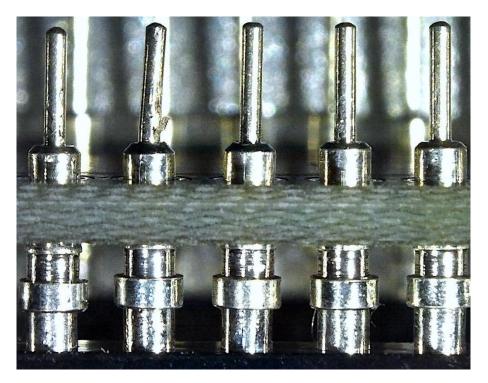


Figure 7: Pin sockets aligned in PCB before soldering

Just add very little solder, so that it just coats the gap between pin socket and solder pad and a meniscus is formed. A smooth, concave meniscus indicates a good wetting (Figure 8).

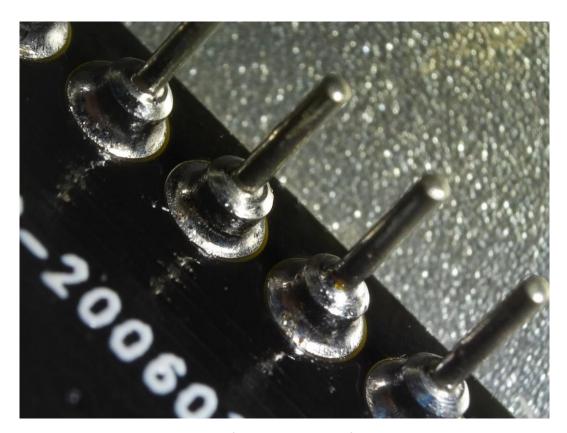


Figure 8: Amount of solder and meniscus of the bottom pads

It is desired that the solder is rising through the pad and also forms a meniscus on the component side (Figure 9). Care must be taken, that the shoulder of the pin sockets is not coated with solder.



Figure 9: Solder meniscus on the top solder pads

Finally, the microMatch connector can be soldered.

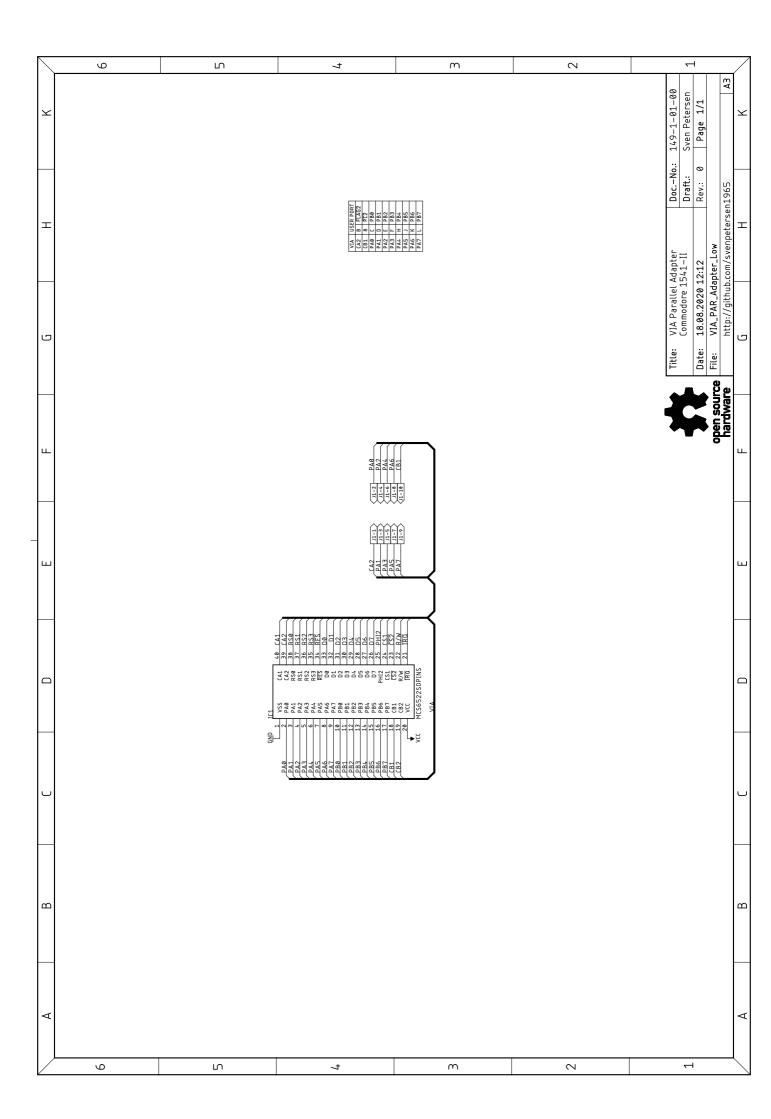
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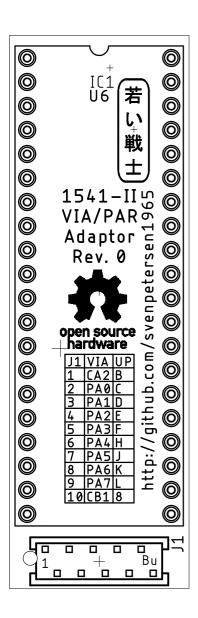
Revision History

Rev. 0

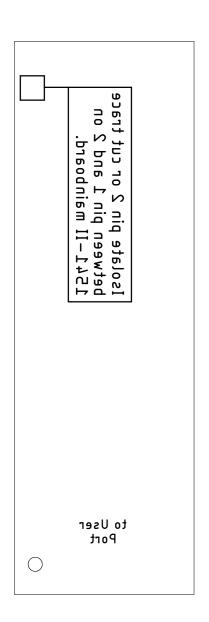
• Prototypes fully functional. For testing consult the documentation of the User Port/Parallel Adapter (Project 150).



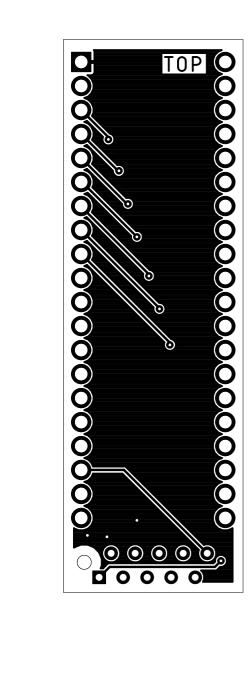
Sven Petersen	DocNo.: 1	49-2-01-00
2020	Cu: 35µm	Cu-Layers: 2
VIA_PAR_Adapter_L	. O W	
18.08.2020 12:12		Rev.: 0
placement component	: side	



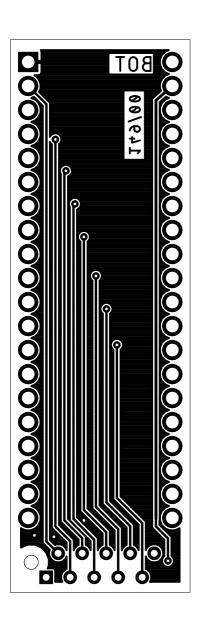
Sven Petersen	DocNo.: 1	49-2-01-00
2020	Cu: 35µm	Cu-Layers: 2
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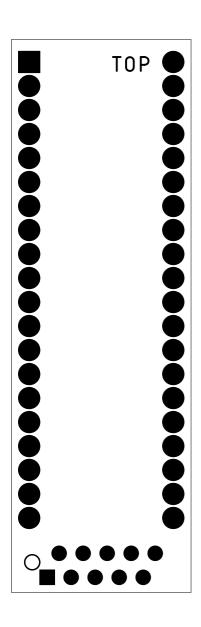
Sven Petersen	Doc.	-No.: 1	49-2-01-00
2020	Cu:	$35\mu m$	Cu-Layers: 2
VIA_PAR_Adapter_L	.0 W		
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top			



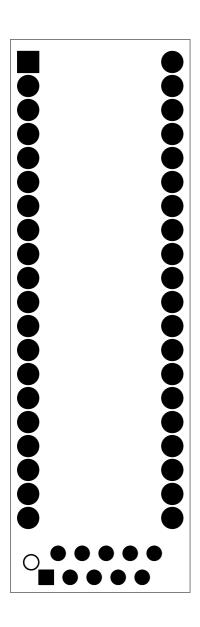
Sven Petersen	DocNo.:	149-2-01-00
2020	Cu: 35µm	Cu-Layers: 2
VIA_PAR_Adapter_L	. o w	
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bottom		



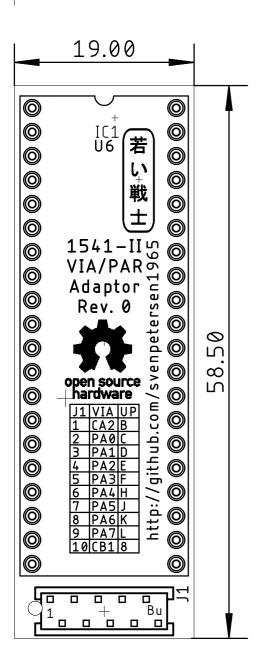
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2020	Cu: 35µm	Cu-Layers: 2
VIA_PAR_Adapter_L	. O W	
18.08.2020 12:12		Rev.: 0
stopmask component	side	

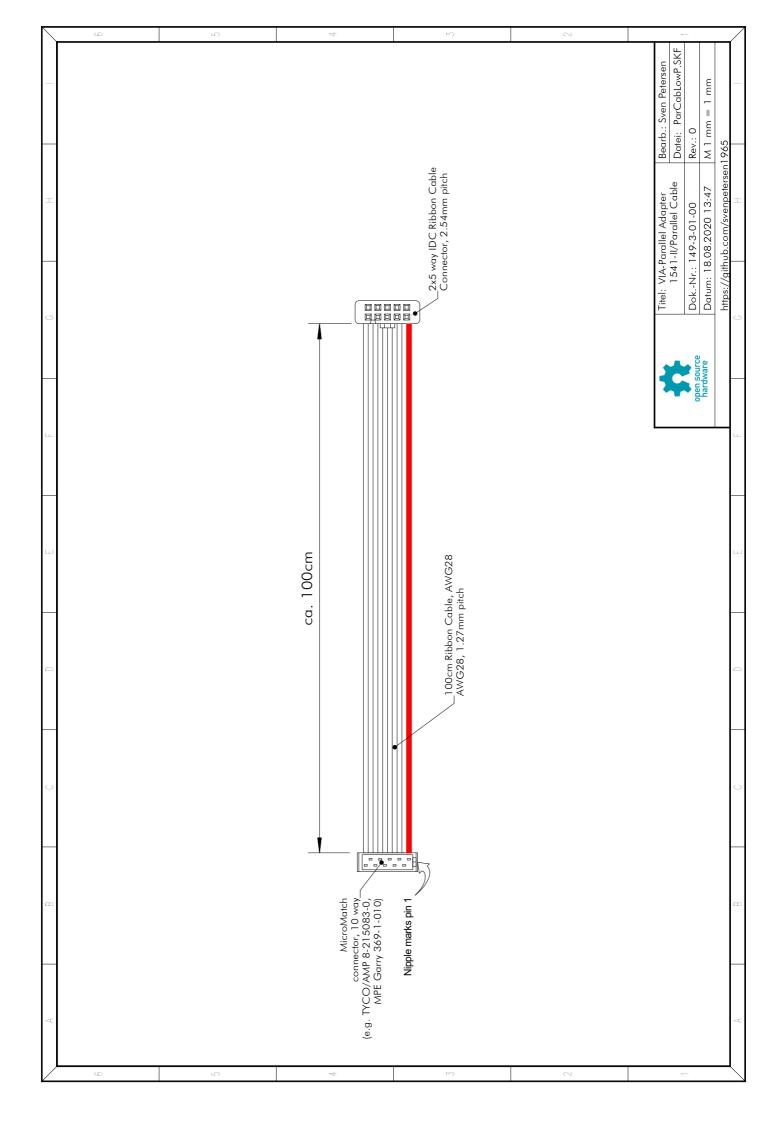


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VIA_PAR_Adapter_L	. O W	
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stopmask solder side		



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VIA_PAR_Adapter_L	. O W	
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placement component	side mea	sures





Commodore 1541-II VIA/Parallel-Adapter Rev. 0 Bill of Material Rev. 0.0

Pos.	Qty Value	Footprint	RefNo.	Comment
_	1 149-2-01-00	2 Layer	PCB Rev. 0	2 layer, Cu 35µ, HASL, 58.5 x 19mm, 1.6mm FR4
2	2 40p DIP Socket	GS40P	IC1	Dual In Line precision round pin Socket, e.g. Reichelt:
				GS40P (the 2nd socket is for alignment), single pins:
				Connfly DS1005-09-468, tme.eu: STS-1P
က	1 8-215079-0	MicroMaTch 10p	ال ه	Tyco/AMP or MPE Garry 369-1-010, e.g. Reichelt MPE 369-
				1-010
4	1 8-215083-0	MicroMaTch 10p	(۱۱) ه	Tyco/AMP (IDC connector) or MPE Garry 372-1-010, , e.g.
				Reichelt MPE 372-1-010
2	1 10p IDC receptacle,			e.g. Reichelt RND 205-00682
	2,54mm			
6 1m	n 10p/AWG28/1,27mm			Ribbon cable. See drawing 149-3-01-**

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